16**∏** 1C

15**∏** 2C

14 3C 13 4C

12**∏** 5C

11 1 6C

10**]** 7С 9] СОМ

D OR N PACKAGE (TOP VIEW)

1B

2В П

3B **∏** 3

4B [

5B []

6B ∏ 6

Ε

7B 🛮 7

2

5

SLIS072 - DECEMBER 1996

- 500-mA Rated Collector Current (Single Output)
- High-Voltage Outputs . . . 50 V
- Output Clamp Diodes
- Inputs Compatible With Various Types of Logic
- Interchangeable With ULN2001A Series

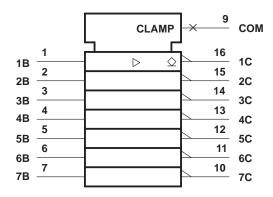
#### description

The ULQ2003A is a monolithic high-voltage, high-current Darlington transistor array. The device consists of seven npn Darlington pairs that

feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of a single Darlington pair is 500 mA. The Darlington pairs may be paralleled for higher current capability. Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers. The ULQ2003A has a 2.7-k $\Omega$  series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS devices.

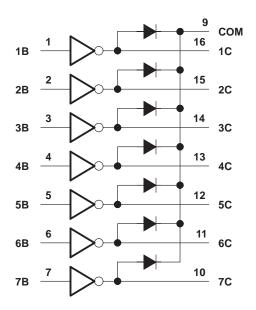
The ULQ2003A is offered in standard 16-pin dual in-line (N) and surface-mount (D) packaging. The device is characterized for operation over the junction temperature range of –40°C to 105°C.

#### logic symbol†



<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)

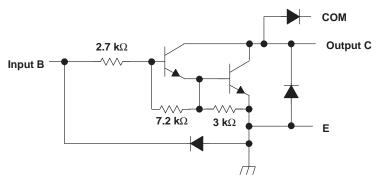




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### schematics (each Darlington pair)



All resistor values shown are nominal.

### absolute maximum ratings over operating temperature range (unless otherwise noted)†

Collector-emitter voltage	
Clamp diode reverse voltage (see Note 1)	
Input voltage, V <sub>I</sub> (see Note 1)	30 V
Peak collector current (see Figures 13 and 14)	500 mA
Output clamp current, I <sub>OK</sub>	500 mA
Total emitter-terminal current	
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	–40°C to 85°C
Operating junction temperature range, T <sub>J</sub>	–40°C to 105°C
Storage temperature range, T <sub>Stq</sub>	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.

#### **DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> = 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING
D	950 mW	7.6 mW/°C	494 mW
N	1150 mW	9.2 mW/°C	598 mW

## electrical characteristics over operating junction temperature range, $T_J = -40$ °C to 105°C

	PARAMETER	TEST CC	ONDITIONS	MIN	TYP	MAX	UNIT
VI(on)	On-state input voltage	V <sub>CE</sub> = 2 V, See Figure 5	$I_C = 200 \text{ mA}$			2.7	V
			$I_C = 250 \text{ mA}$			2.9	
			$I_C = 300 \text{ mA}$			3	
VCE(sat)	Collector-emitter saturation voltage	I <sub>I</sub> = 250 μA, See Figure 4	$I_C = 100 \text{ mA},$		0.9	1.2	
		I <sub>I</sub> = 350 μA, See Figure 4	I <sub>C</sub> = 200 mA,		1	1.4	V
		I <sub>I</sub> = 500 μA, See Figure 4	I <sub>C</sub> = 350 mA,		1.2	1.7	
ICEX	Collector cutoff current	V <sub>CE</sub> = 50 V, See Figure 1	$I_{\parallel} = 0$ ,			100	μΑ
٧F	Clamp forward voltage	$I_F = 350 \text{ mA},$	See Figure 7		1.7	2.2	V
I <sub>I(off)</sub>	Off-state input current	VCE = 50 V, See Figure 2	I <sub>C</sub> = 500 μA,	30	65		μΑ
I <sub>I</sub>	Input current	V <sub>I</sub> = 3.85 V,	See Figure 3		0.93	1.35	mA
I <sub>R</sub>	Clamp reverse current	$V_R = 50 V$ ,	See Figure 6			100	μΑ
Ci	Input capacitance	V <sub>I</sub> = 0,	f = 1 MHz		15	25	pF

# switching characteristics over operating junction temperature, $T_J = -40^{\circ}C$ to $105^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	See Figure 8		1	10	μs
tPHL	Propagation delay time, high-to-low-level output	See Figure 6		1	10	μs
Vон	High-level output voltage after switching	$V_S = 50 \text{ V}, \qquad I_O \approx 300 \text{ mA},$ See Figure 9	V <sub>S</sub> -500			mV

#### PARAMETER MEASUREMENT INFORMATION

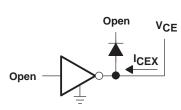


Figure 1. I<sub>CEX</sub> Test Circuit

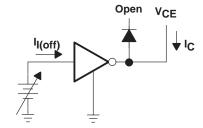


Figure 2. I<sub>I(off)</sub> Test Circuit

#### PARAMETER MEASUREMENT INFORMATION

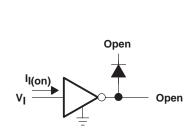


Figure 3. I<sub>I</sub> Test Circuit

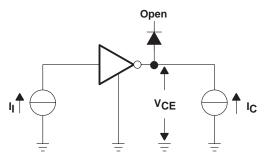


Figure 4. V<sub>CE(sat)</sub> Test Circuit

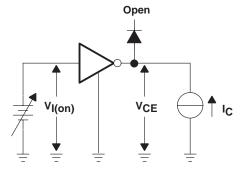


Figure 5. V<sub>I(on)</sub> Test Circuit

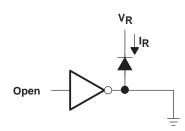


Figure 6. I<sub>R</sub> Test Circuit

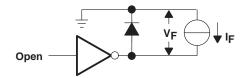


Figure 7. V<sub>F</sub> Test Circuit

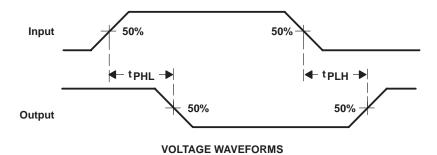
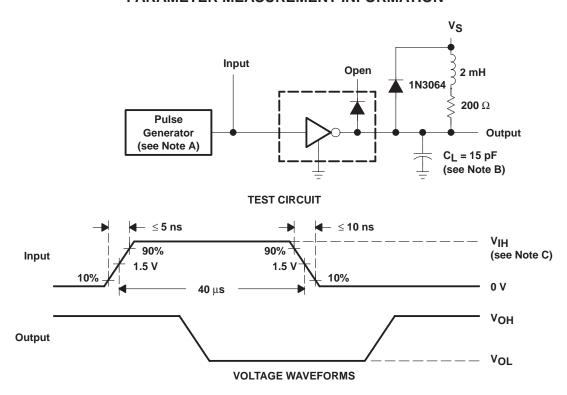


Figure 8. Propagation Delay Time Waveforms

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz,  $Z_O$  = 50  $\Omega$ .

B. C<sub>L</sub> includes probe and jig capacitance.

C. V<sub>IH</sub> = 3 V

Figure 9. Latch-Up Test Circuit and Voltage Waveforms

#### TYPICAL CHARACTERISTICS

#### **COLLECTOR-EMITTER SATURATION VOLTAGE COLLECTOR CURRENT** (ONE DARLINGTON) 2.5 VCE(sat) - Collector-Emitter Saturation Voltage - V 2 $I_{|} = 250 \mu A$ $I_1 = 350 \mu A$ $I_I = 500 \mu A$ 1.5 1 0.5 0 0 100 800 200 300 400 500 600 700 I<sub>C</sub> - Collector Current - mA

Figure 10

# COLLECTOR-EMITTER SATURATION VOLTAGE vs TOTAL COLLECTOR CURRENT

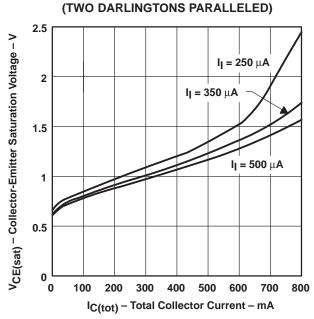


Figure 11

#### **COLLECTOR CURRENT**

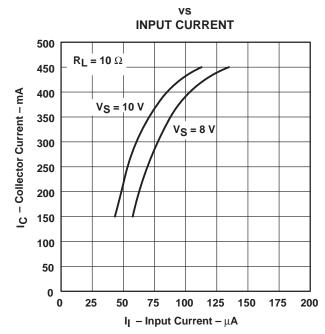


Figure 12

#### THERMAL INFORMATION

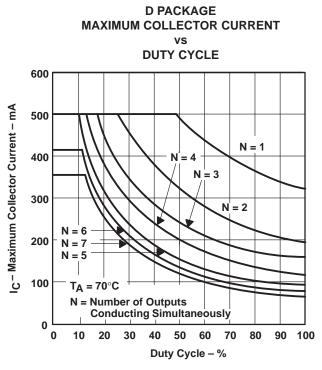
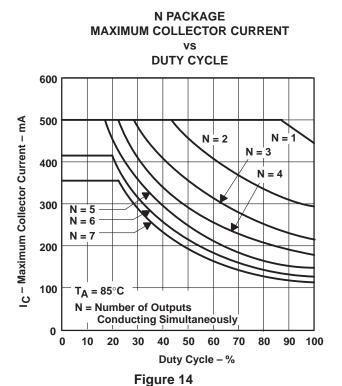


Figure 13



TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

#### **APPLICATION INFORMATION**

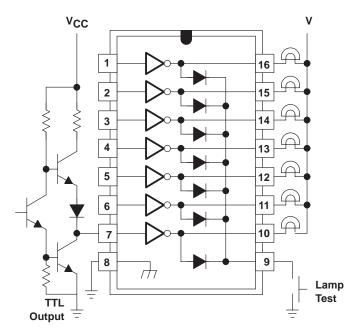


Figure 15. TTL to Load

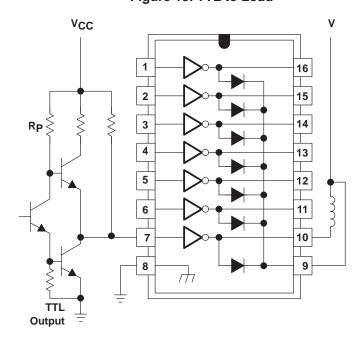


Figure 16. Use of Pullup Resistors to Increase Drive Current



#### **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated

# This datasheet has been downloaded from:

www. Data sheet Catalog.com

Datasheets for electronic components.